



## **Dual P-Channel 20-V (D-S) MOSFET**

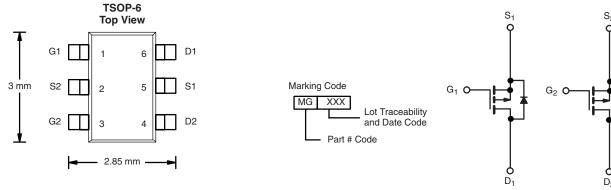
PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
- 20	$0.115$ at $V_{GS} = -4.5 \text{ V}$	<sub>S</sub> = - 4.5 V - 2.7				
- 20	0.205 at V <sub>GS</sub> = - 2.5 V	- 2.0	3.2 nC			

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- · PWM Optimized
- 100 % R<sub>q</sub> Tested
- Compliant to RoHS Directive 2002/95/EC







Ordering Information: Si3951DV-T1-E3 (Lead (Pb)-free)

Si3951DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET	P-Channel MOSFFT

<b>ABSOLUTE MAXIMUM RATIN</b>	<b>IGS</b> T <sub>A</sub> = 25 °C,	unless othe	rwise noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		$V_{DS}$	- 20	V	
Gate-Source Voltage		$V_{GS}$	± 12	v	
	T <sub>C</sub> = 25 °C		- 2.7		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	- 2.2		
Continuous Diam Current (1) = 130 C)	T <sub>A</sub> = 25 °C		- 2.5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		- 2.0 <sup>b, c</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	10		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I <sub>S</sub>	- 1.67		
	T <sub>A</sub> = 25 °C		- 0.95 <sup>b, c</sup>		
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C		2.0		
	T <sub>C</sub> = 70 °C	P <sub>D</sub>	1.3	w	
	T <sub>A</sub> = 25 °C	' D	1.14 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C	]	0.73 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	l Maximum			
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	$R_{thJA}$	93	93 110 °C/V			
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	75	90	O/ <b>VV</b>		

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- $c. \quad t=5 \ s.$
- d. Maximum under Steady State conditions is 130 °C/W.

## Si3951DV

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250A		- 16.7		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.1			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = -250 \ \mu A$	- 0.6		- 1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1		
		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 10			A	
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS} = -4.5 \text{ V}, I_D = -2.5 \text{ A}$		0.092	0.115	Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 1.8 A		0.164	0.205		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 2.5 A		5.5		S	
Dynamic <sup>b</sup>				l .	l .		
Input Capacitance	C <sub>iss</sub>			250		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		80			
Reverse Transfer Capacitance	C <sub>rss</sub>			55			
Total Cata Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -5.0 \text{ V}, I_{D} = -2.5 \text{ A}$		3.4	5.1	nC	
Total Gate Charge	Qg			3.2	5		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -2.5 \text{ A}$		0.5			
Gate-Drain Charge	Q <sub>gd</sub>			1.4			
Gate Resistance	$R_{g}$	f = 1 MHz		8.5	13	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			9	14		
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 10 V, $R_L$ = 5 $\Omega$		30	45	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 2 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		32	48		
Fall Time	t <sub>f</sub>			16	24		
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 1.7	A	
Pulse Diode Forward Current	I <sub>SM</sub>				- 10		
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 2.0 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			17	26	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			5	8	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -2.0 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		14		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			3			

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %

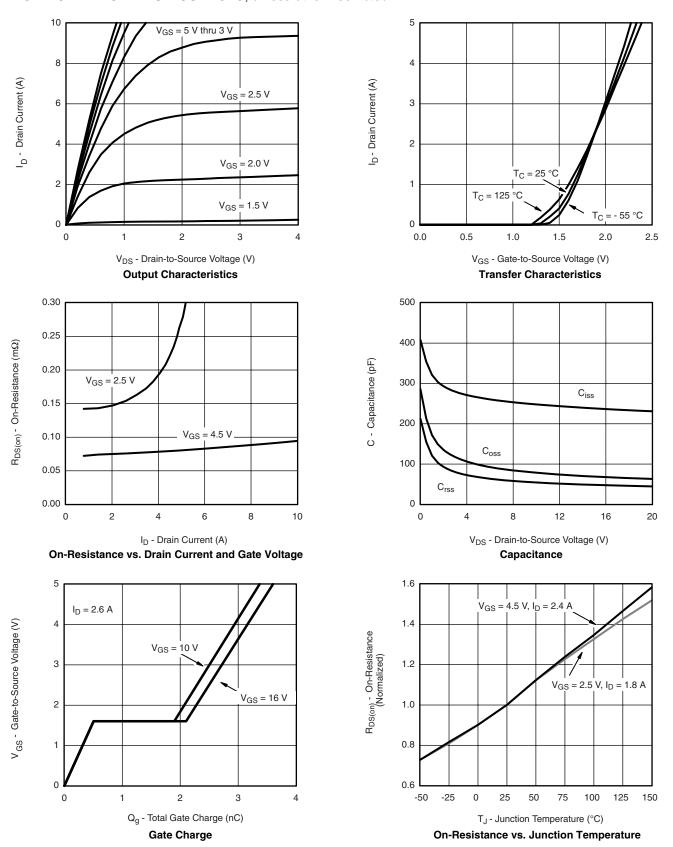
b. Guaranteed by design, not subject to production testing.







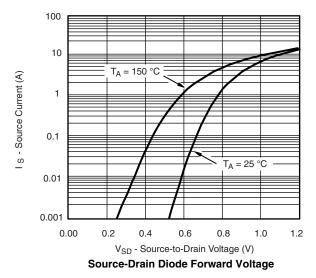
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

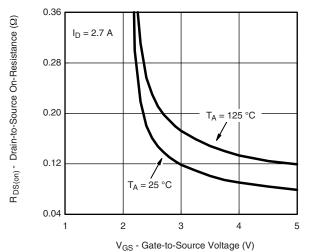


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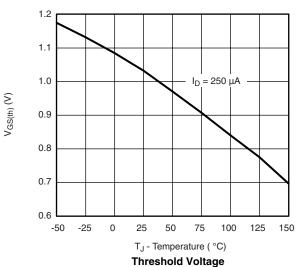
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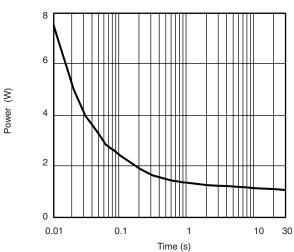
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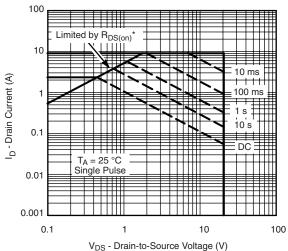








Single Pulse Power (Junction-to-Ambient)



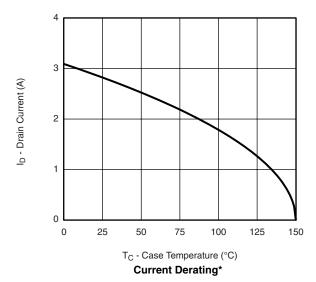
 $v_{DS}$  - Drain-to-Source voltage (v) \*  $v_{GS}$  > minimum  $v_{GS}$  at which  $v_{DS(on)}$  is specified Safe Operating Area

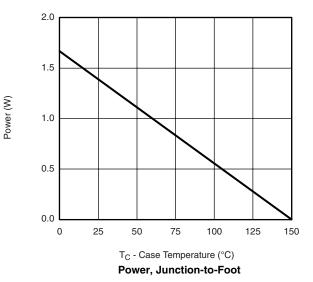




## Si3951DV Vishay Siliconix

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



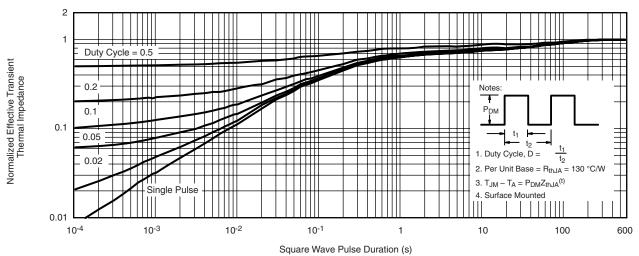


 $<sup>^*</sup>$  The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package

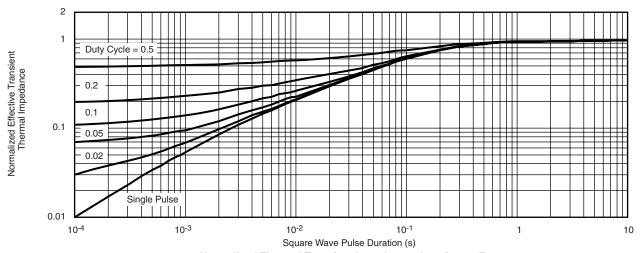
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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